SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

17 🛛 3Y

16 3A

15 3,4EN

2Y 🛛 12

13

 Featuring Unitrode L293 and L293D Products Now From Texas Instruments 	N, NE PACKAGE (TOP VIEW)				
 Wide Supply-Voltage Range: 4.5 V to 36 V 	1,2EN 1 16 V _{CC1}				
 Separate Input-Logic Supply 					
Internal ESD Protection	1Y 🛛 3 14 🗍 4Y				
Thermal Shutdown	HEAT SINK AND $\int \left[4 \right]^4 = 13 \left[-3 \right]$ HEAT SINK AND				
High-Noise-Immunity Inputs	GROUND GROUND				
• Functional Replacements for SGS L293 and	2Y [] 6 11 [] 3Y 2A [] 7 10 [] 3A				
SGS L293D	V _{CC2} [8 9] 3,4EN				
Output Current 1 A Per Channel (200 m A (see L 202D)					
(600 mA for L293D)					
 Peak Output Current 2 A Per Channel (1.2 A for L293D) 					
 Output Clamp Diodes for Inductive 	1,2EN [] 1 28 [] V _{CC1}				
Transient Suppression (L293D)	1A [] 2 27 [] 4A				
description					
The LOO2 and LOO2D are supdruple high surrout	NC [] 5 24 [] NC NC [] 6 23 [] NC				
The L293 and L293D are quadruple high-current half-H drivers. The L293 is designed to provide					
bidirectional drive currents of up to 1 A at voltages	HEAT SINK AND GROUND				
from 4.5 V to 36 V. The L293D is designed to					
provide bidirectional drive currents of up to					
600-mA at voltages from 4.5 V to 36 V. Both	NC 🛛 11 18 🗍 NC				

All inputs are TTL compatible. Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression.

A V_{CC1} terminal, separate from V_{CC2}, is provided for the logic inputs to minimize device power dissipation.

The L293and L293D are characterized for operation from 0°C to 70°C.

devices are designed to drive inductive loads such

as relays, solenoids, dc and bipolar stepping

motors, as well as other high-current/high-voltage

loads in positive-supply applications.



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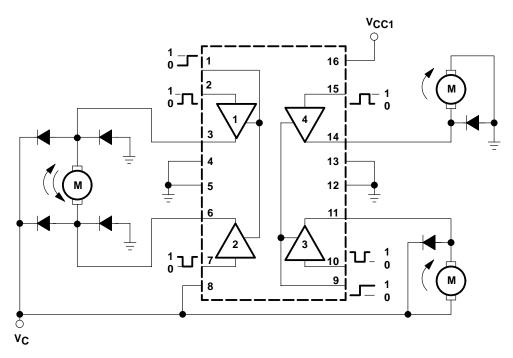
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block diagram



NOTE: Output diodes are internal in L293D.

TEXAS INSTRUMENTS AVAILABLE OPTIONS

	PACKAGE
TA	PLASTIC DIP (NE)
0°C to 70°C	L293NE L293DNE

Unitrode Products from Texas Instruments AVAILABLE OPTIONS				
т.	PACKAGED DEVICES			
TA	OUTLINE (DWP)	DIP (N)		
0°C to 70°C	L293DWP L293DDWP	L293N L293DN		

The DWP package is available taped and reeled. Add the suffix TR to device type (e.g., L293DWPTR).



SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

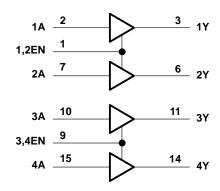
FUNCTION TABLE (each driver)

INPU	JTS†	OUTPUT
Α	EN	Y
Н	Н	Н
L	Н	L
Х	L	Z

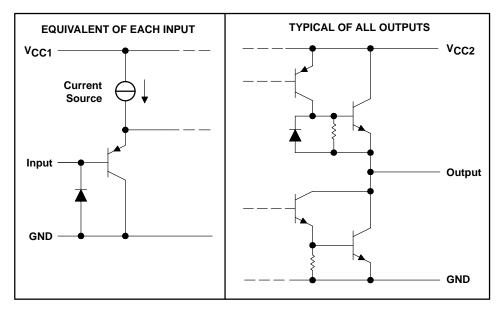
H = high level, L = low level, X = irrelevant, Z = high impedance (off)

[†] In the thermal shutdown mode, the output is in the high-impedance state, regardless of the input levels.

logic diagram



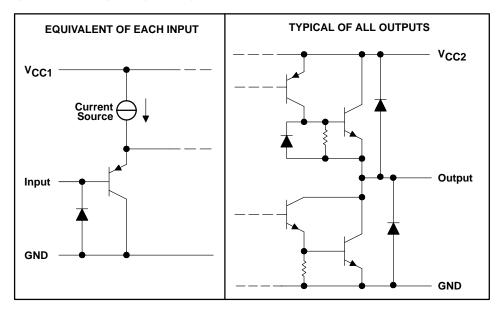
schematics of inputs and outputs (L293)





SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

schematics of inputs and outputs (L293D)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC1} (see Note 1)	
Output supply voltage, V _{CC2}	
Output voltage range, V _O	
Peak output current, I_{O} (nonrepetitive, t \leq 5 ms): L293	
Peak output current, I_O (nonrepetitive, t \leq 100 μ s): L293D	±1.2 A
Continuous output current, I _O : L293	±1 A
Continuous output current, Io: L293D	±600 mA
Continuous total dissipation at (or below) 25°C free-air temperature (see Notes 2 and 3)	2075 mW
Continuous total dissipation at 80°C case temperature (see Note 3)	5000 mW
Maximum junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to the network ground terminal.

2. For operation above 25°C free-air temperature, derate linearly at the rate of 16.6 mW/°C.

3. For operation above 25°C case temperature, derate linearly at the rate of 71.4 mW/°C. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.



SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

recommended operating conditions

		MIN	MAX	UNIT
	V _{CC1}	4.5	7	V
	Supply voltage V _{CC2}	VCC1	36	v
V	High-level input voltage $V_{CC1} \le 7 V$	2.3	V _{CC1}	V
VIH	V _{CC1} \ge 7 V	2.3	7	V
V_{IL}	-0.3†	1.5	V	
Т _А	Operating free-air temperature	0	70	°C

[†] The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

electrical characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

	PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT	
VOH	High-level output voltage		L293: I _{OH} : L293D: I _{OH}		V _{CC2} -1.8	V _{CC2} -1.4		V	
V _{OL}	Low-level output voltage	utput voltage		= 1 A = 0.6 A		1.2	1.8	V	
Vокн	High-level output clamp v	oltage	L293D: IOK	=-0.6 A		V _{CC2} + 1.3		V	
VOKL	Low-level output clamp vo	oltage	L293D: IOK	= 0.6 A		1.3		V	
I	I _{IH} High-level input current A EN		- V _I = 7 V			0.2	100		
ЧН						0.2	10	μA	
1	Low-level input current	А	$\lambda = 0$			-3	-10		
ΙL	Low-level input current	EN	V ₁ = 0			-2	-100	μΑ	
				All outputs at high level		13	22		
ICC1	1 Logic supply current		IO = 0	All outputs at low level		35	60	mA	
				All outputs at high impedance		8	24		
				All outputs at high level		14	24		
ICC2	Output supply current $I_{O} = 0$	IO = 0	All outputs at low level		2	6	mA		
				All outputs at high impedance		2	4		

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

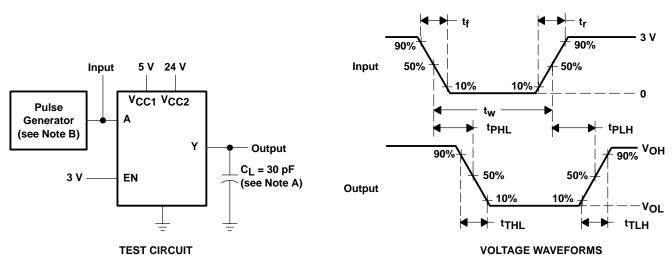
	PARAMETER	TEST CONDITIONS	L293NE, L293DNE			UNIT
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	
^t PLH	Propagation delay time, low-to-high-level output from A input			800		ns
^t PHL	Propagation delay time, high-to-low-level output from A input			400		ns
^t TLH	Transition time, low-to-high-level output	C _L = 30 pF, See Figure 1		300		ns
^t THL	Transition time, high-to-low-level output			300		ns

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	L293DWP, L293N L293DDWP, L293DN			UNIT
			MIN	TYP	MAX	
^t PLH	Propagation delay time, low-to-high-level output from A input			750		ns
t _{PHL}	Propagation delay time, high-to-low-level output from A input			200		ns
t _{TLH}	Transition time, low-to-high-level output	C _L = 30 pF, See Figure 1 100			ns	
^t THL	Transition time, high-to-low-level output			350		ns



SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002



PARAMETER MEASUREMENT INFORMATION

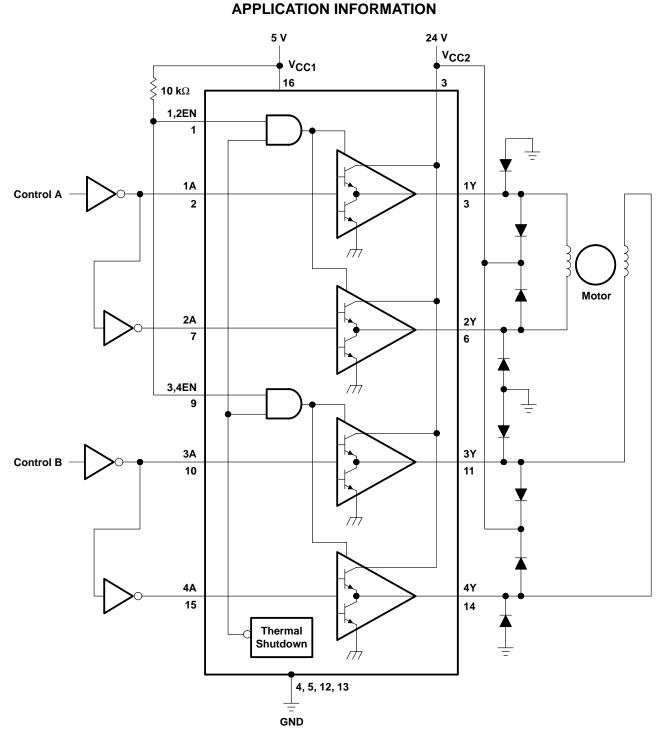
NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $t_f \le 10$ ns, $t_f \le 10$ ns, $t_w = 10 \ \mu$ s, PRR = 5 kHz, $Z_O = 50 \ \Omega$.

Figure 1. Test Circuit and Voltage Waveforms



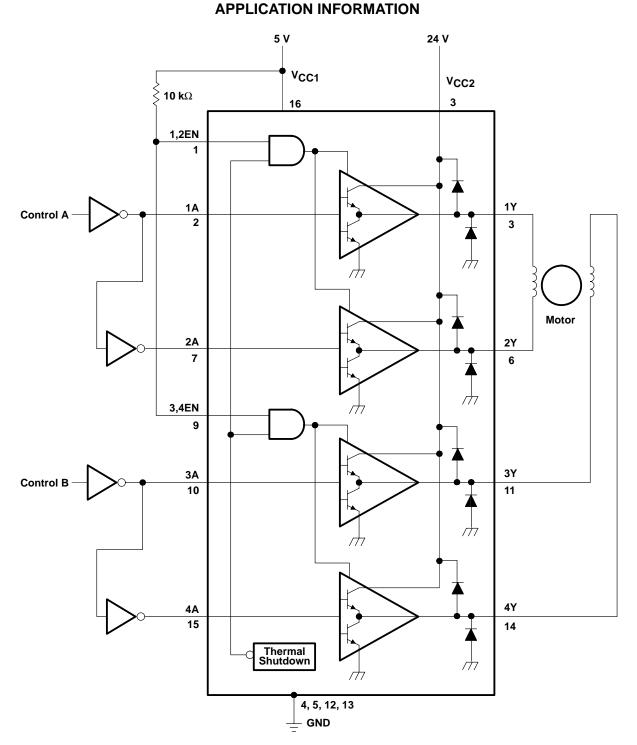
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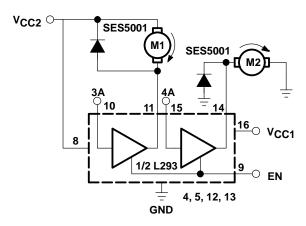


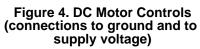




SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

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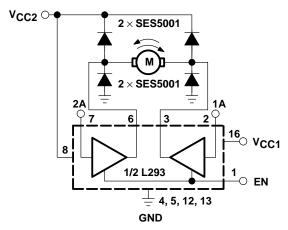


Figure 5. Bidirectional DC Motor Control

EN	3A	M1	4A	M2
Н	Н	Fast motor stop	Н	Run
Н	L	Run	L	Fast motor stop
L	х	Free-running motor stop	х	Free-running motor stop

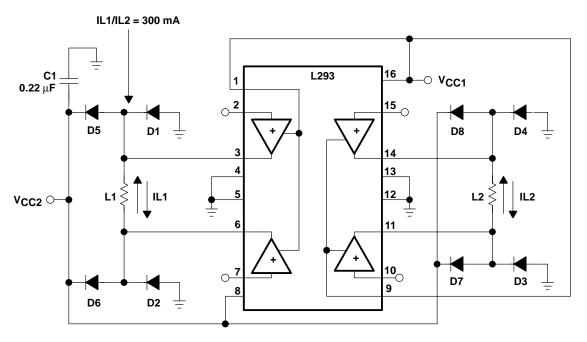
L = low, H = high, X = don't care

EN	1A	2A	FUNCTION
н	L	Н	Turn right
н	Н	L	Turn left
н	L	L	Fast motor stop
н	Н	Н	Fast motor stop
L	Х	Х	Fast motor stop

L = low, H = high, X = don't care



SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002



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D1-D8 = SES5001

Figure 6. Bipolar Stepping-Motor Control

mounting instructions

The Rthj-amp of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heatsink.

Figure 9 shows the maximum package power P_{TOT} and the θ_{JA} as a function of the side l of two equal square copper areas having a thickness of 35 μ m (see Figure 7). In addition, an external heat sink can be used (see Figure 8).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.



SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

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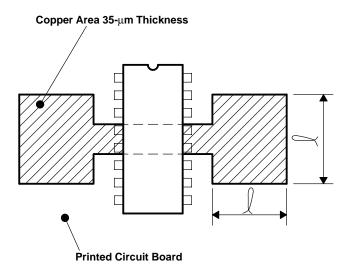
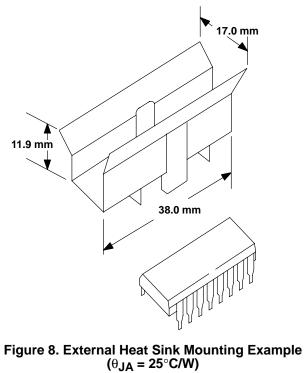


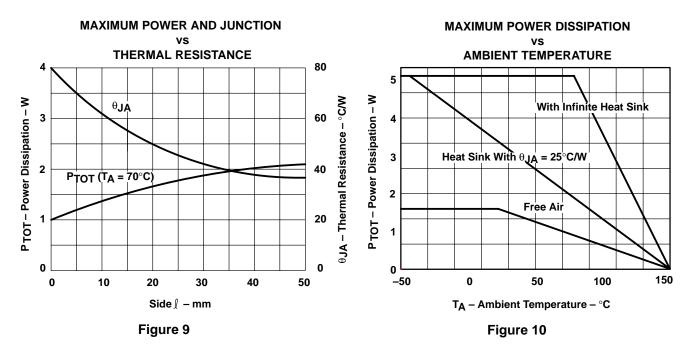
Figure 7. Example of Printed Circuit Board Copper Area (used as heat sink)





SLRS008B - SEPTEMBER 1986 - REVISED JUNE 2002

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